### T3. Advances in Manufacturing and Processing Technologies

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<th>Session Date:</th>
<th>March 7 (Tue.), 2023</th>
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<td>Session Time:</td>
<td>9:00-12:20</td>
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#### [T3-1] 09:00-10:00

**Introduction to Advanced Packaging Technology for HI**  
Sarah Eunkyung Kim  
*Seoul National University of Science and Technology*

#### [T3-2] 10:10-11:10

**The Value of Memory Packaging in Heterogeneous Integration**  
Ki-Ill Moon  
*SK Hynix*

#### [T3-3] 11:20-12:20

**HI PIM AI Processor’s Perspective on HI Architecture, HBM3/4 Integration, PHY, PI/SI, Interposer, and Substrate**  
Youngsu Kwon  
*ETRI*